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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f6410-e-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



### FIGURE 1-1: PIC18F6310/6410 (64-PIN) BLOCK DIAGRAM

Note 1: CCP2 is multiplexed with RC1 when Configuration bit, CCP2MX, is set or RE7 when CCP2MX is not set.

**2:** RG5 is only available when  $\overline{MCLR}$  functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. Refer to Section 3.0 "Oscillator Configurations" for additional information.

Din Nome	Pin Number	Pin	Buffer	Description				
Pin Name	TQFP	Туре	P Type Description					
				PORTE is a bidirectional I/O port.				
RE0/RD RE0 RD	2	I/O I	ST TTL	Digital I/O. Read control for Parallel Slave Port.				
RE1/WR RE1 WR	1	I/O I	ST TTL	Digital I/O. Write control for Parallel Slave Port.				
RE2/CS RE2 CS	64	I/O I	ST TTL	Digital I/O. Chip select control for Parallel Slave Port.				
RE3	63	I/O	ST	Digital I/O.				
RE4	62	I/O	ST	Digital I/O.				
RE5	61	I/O	ST	Digital I/O.				
RE6	60	I/O	ST	Digital I/O.				
RE7/CCP2 RE7 CCP2 <sup>(2)</sup>	59	I/O I/O	ST ST	Digital I/O. Capture 2 input/Compare 2 output/PWM2 output.				
Legend:TTL = TTL compatible inputCMOS = CMOS compatible input or outputST = Schmitt Trigger input with CMOS levelsAnalog = Analog inputI = InputO = OutputP = Power $l^2C = ST$ with $l^2C^{TM}$ or SMB levels								
Note 1: Default assig	1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.							

### TABLE 1-2: PIC18F6310/6410 PINOUT I/O DESCRIPTIONS (CONTINUED)

Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
 Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

# TABLE 3-2:CAPACITOR SELECTION FOR<br/>CRYSTAL OSCILLATOR

Osc Type	Crystal	Typical Capacitor Value Tested:		
	Fieq	C1	C2	
LP	32 kHz	33 pF	33 pF	
	200 kHz	15 pF	15 pF	
XT	1 MHz	33 pF	33 pF	
	4 MHz	27 pF	27 pF	
HS	4 MHz	27 pF	27 pF	
	8 MHz	22 pF	22 pF	
	20 MHz	15 pF	15 pF	

#### Capacitor values are for design guidance only.

These capacitors were tested with the crystals listed below for basic start-up and operation. **These values are not optimized.** 

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following this table for additional information.

Crystals Used:					
32 kHz	4 MHz				
200 kHz	8 MHz				
1 MHz	20 MHz				

- Note 1: Higher capacitance increases the stability of oscillator, but also increases the start-up time.
  - When operating below 3V VDD, or when using certain ceramic resonators at any voltage, it may be necessary to use the HS mode or switch to a crystal oscillator.
  - Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
  - 4: Rs may be required to avoid overdriving crystals with low drive level specification.
  - **5:** Always verify oscillator performance over the VDD and temperature range that is expected for the application.

An external clock source may also be connected to the OSC1 pin in the HS mode, as shown in Figure 3-2.



### 3.3 External Clock Input

The EC and ECIO Oscillator modes require an external clock source to be connected to the OSC1 pin. There is no oscillator start-up time required after a Power-on Reset or after an exit from Sleep mode.

In the EC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 3-3 shows the pin connections for the EC Oscillator mode.





The ECIO Oscillator mode functions like the EC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 3-4 shows the pin connections for the ECIO Oscillator mode.



#### EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



The PLUSW register can be used to implement a form of Indexed Addressing in the data memory space. By manipulating the value in the W register, users can reach addresses that are fixed offsets from pointer addresses. In some applications, this can be used to implement some powerful program control structure, such as software stacks, inside of data memory.

### 6.4.3.3 Operations by FSRs on FSRs

Indirect Addressing operations that target other FSRs or virtual registers represent special cases. For example, using an FSR to point to one of the virtual registers will not result in successful operations. As a specific case, assume that FSR0H:FSR0L contains FE7h, the address of INDF1. Attempts to read the value of the INDF1, using INDF0 as an operand, will return 00h. Attempts to write to INDF1, using INDF0 as the operand, will result in a NOP.

On the other hand, using the virtual registers to write to an FSR pair may not occur as planned. In these cases, the value will be written to the FSR pair, but without any incrementing or decrementing. Thus, writing to INDF2 or POSTDEC2 will write the same value to the FSR2H:FSR2L.

Since the FSRs are physical registers mapped in the SFR space, they can be manipulated through all direct operations. Users should proceed cautiously when working on these registers, particularly if their code uses Indirect Addressing.

Similarly, operations by Indirect Addressing are generally permitted on all other SFRs. Users should exercise the appropriate caution that they do not inadvertently change settings that might affect the operation of the device.

# 6.5 Data Memory and the Extended Instruction Set

Enabling the PIC18 extended instruction set (XINST Configuration bit = 1) significantly changes certain aspects of data memory and its addressing. Specifically, the use of the Access Bank for many of the core PIC18 instructions is different; this is due to the introduction of a new addressing mode for the data memory space.

What does not change is just as important. The size of the data memory space is unchanged, as well as its linear addressing. The SFR map remains the same. Core PIC18 instructions can still operate in both Direct and Indirect Addressing mode; inherent and literal instructions do not change at all. Indirect Addressing with FSR0 and FSR1 also remain unchanged.

### 6.5.1 INDEXED ADDRESSING WITH LITERAL OFFSET

Enabling the PIC18 extended instruction set changes the behavior of Indirect Addressing using the FSR2 register pair and its associated file operands. Under the proper conditions, instructions that use the Access Bank – that is, most bit-oriented and byte-oriented instructions – can invoke a form of Indexed Addressing using an offset specified in the instruction. This special addressing mode is known as Indexed Addressing with Literal Offset, or Indexed Literal Offset mode.

When using the extended instruction set, this addressing mode requires the following:

- The use of the Access Bank is forced ('a' = 0); and
- The file address argument is less than or equal to 5Fh.

Under these conditions, the file address of the instruction is not interpreted as the lower byte of an address (used with the BSR in Direct Addressing), or as an 8-bit address in the Access Bank. Instead, the value is interpreted as an offset value to an Address Pointer specified by FSR2. The offset and the contents of FSR2 are added to obtain the target address of the operation.

### 6.5.2 INSTRUCTIONS AFFECTED BY INDEXED LITERAL OFFSET MODE

Any of the core PIC18 instructions that can use Direct Addressing are potentially affected by the Indexed Literal Offset Addressing mode. This includes all byte-oriented and bit-oriented instructions, or almost one-half of the standard PIC18 instruction set. Instructions that only use Inherent or Literal Addressing modes are unaffected.

Additionally, byte-oriented and bit-oriented instructions are not affected if they do not use the Access Bank (Access RAM bit is '1'), or include a file address of 60h or above. Instructions meeting these criteria will continue to execute as before. A comparison of the different possible addressing modes when the extended instruction set is enabled is shown in Figure 6-9.

Those who desire to use byte-oriented or bit-oriented instructions in the Indexed Literal Offset mode should note the changes to assembler syntax for this mode. This is described in more detail in **Section 25.2.1** "Extended Instruction Syntax".

### 7.0 PROGRAM MEMORY

For PIC18FX310/X410 devices, the on-chip program memory is implemented as read-only memory. It is readable over the entire VDD range during normal operation; it cannot be written to or erased. Reads from program memory are executed one byte at a time.

PIC18F8410 devices also implement the ability to read, write to and execute code from external memory devices using the external memory interface. In this implementation, external memory is used as all or part of the program memory space. The operation of the physical interface is discussed in **Section 8.0 "External Memory Interface"**.

In all devices, a value written to the program memory space does not need to be a valid instruction. Executing a program memory location that forms an invalid instruction results in a NOP.

### 7.1 Table Reads and Table Writes

To read and write to the program memory space, there are two operations that allow the processor to move bytes between the program memory space and the data RAM: table read (TBLRD) and table write (TBLWT).

The program memory space is 16 bits wide, while the data RAM space is 8 bits wide. Table reads and table writes move data between these two memory spaces through an 8-bit register (TABLAT).

Table read operations retrieve data from program memory and places it into the data RAM space. Table write operations place data from the data memory space on the external data bus. The actual process of writing the data to the particular memory device is determined by the requirements of the device itself. Figure 7-1 shows the table operations as they relate to program memory and data RAM.

Table operations work with byte entities. A table block containing data, rather than program instructions, is not required to be word-aligned. Therefore, a table block can start and end at any byte address. If a table write is being used to write executable code into an external program memory, program instructions will need to be word-aligned.

Note: Although it cannot be used in PIC18F6310 devices in normal operation, the TBLWT instruction is still implemented in the instruction set. Executing the instruction takes two instruction cycles, but effectively results in a NOP. The TBLWT instruction is available in programming modes and is used during In-Circuit Serial Programming (ICSP).

### FIGURE 7-1: TABLE READ AND TABLE WRITE OPERATIONS



### 8.3 8-Bit Mode

The external memory interface implemented in PIC18F8410 devices operates only in 8-Bit Multiplexed mode; data shares the 8 Least Significant bits of the address bus.

Figure 8-1 shows an example of 8-Bit Multiplexed mode for PIC18F8410 devices. This mode is used for a single 8-bit memory connected for 16-bit operation. The instructions will be fetched as two 8-bit bytes on a shared data/address bus. The two bytes are sequentially fetched within one instruction cycle (TcY). Therefore, the designer must choose external memory devices according to timing calculations based on 1/2 TcY (2 times the instruction rate). For proper memory speed selection, glue logic propagation delay times must be considered along with setup and hold times.

The Address Latch Enable (ALE) pin indicates that the address bits, A<15:0>, are available on the external memory interface bus. The Output Enable signal ( $\overline{OE}$ ) will enable one byte of program memory for a portion of the instruction cycle, then BA0 will change and the second byte will be enabled to form the 16-bit instruction word. The Least Significant bit of the address, BA0, must be connected to the memory devices in this mode. The Chip Enable signal ( $\overline{CE}$ ) is active at any time that the microcontroller accesses external memory, whether reading or writing; it is inactive (asserted high) whenever the device is in Sleep mode.

This generally includes basic EPROM and Flash devices. It allows table writes to byte-wide external memories.

During a TBLWT instruction cycle, the TABLAT data is presented on the upper and lower bytes of the AD<15:0> bus. The appropriate level of the BA0 control line is strobed on the LSb of the TBLPTR.



### FIGURE 8-7: 8-BIT MULTIPLEXED MODE EXAMPLE

### 9.0 8 x 8 HARDWARE MULTIPLIER

### 9.1 Introduction

All PIC18 devices include an 8 x 8 hardware multiplier as part of the ALU. The multiplier performs an unsigned operation and yields a 16-bit result that is stored in the product register pair PRODH:PRODL. The multiplier's operation does not affect any flags in the STATUS register.

Making multiplication a hardware operation allows it to be completed in a single instruction cycle. This has the advantages of higher computational throughput and reduced code size for multiplication algorithms and allows the PIC18 devices to be used in many applications previously reserved for digital signal processors. A comparison of various hardware and software multiply operations, along with the savings in memory and execution time, is shown in Table 9-1.

### 9.2 Operation

Example 9-1 shows the instruction sequence for an 8 x 8 unsigned multiplication. Only one instruction is required when one of the arguments is already loaded in the WREG register.

Example 9-2 shows the sequence to do an 8 x 8 signed multiplication. To account for the sign bits of the arguments, each argument's Most Significant bit (MSb) is tested and the appropriate subtractions are done.

### EXAMPLE 9-1: 8 x 8 UNSIGNED MULTIPLY ROUTINE

MOVF	ARG1,	w a	;	
MULWF	ARG2	i	;	ARG1 * ARG2 ->
		i	;	PRODH:PRODL

# EXAMPLE 9-2: 8 x 8 SIGNED MULTIPLY

		INC.		
MOVF	ARG1, W			
MULWF	ARG2	;	ARG1 * ARG2 ->	
		;	PRODH:PRODL	
BTFSC	ARG2, SB	;	Test Sign Bit	
SUBWF	PRODH, F	;	PRODH = PRODH	
		;	- ARG1	
MOVF	ARG2, W			
BTFSC	ARG1, SB	;	Test Sign Bit	
SUBWF	PRODH, F	;	PRODH = PRODH	
		;	- ARG2	

		Program	Cycles	Time			
Routine	Multiply Method	Memory (Words)	(Max)	@ 40 MHz	@ 10 MHz	@ 4 MHz	
9 x 9 Unsigned	Without Hardware Multiply	13	69	6.9 μs	27.6 μs	69 μ <b>s</b>	
8 x 8 Unsigned	Hardware Multiply	1	1	100 ns	400 ns	1 μs	
0 x 0 Cignod	Without Hardware Multiply	33	91	9.1 μs	36.4 μs	91 μs	
o x o Sigrieu	Hardware Multiply	6	6	600 ns	2.4 μs	6 μs	
16 x 16 Upsigned	Without Hardware Multiply	21	242	24.2 μs	96.8 μs	242 μs	
To X To Unsigned	Hardware Multiply	28	28	2.8 μs	11.2 μs	28 μs	
16 x 16 Signod	Without Hardware Multiply	52	254	25.4 μs	102.6 μs	254 μs	
To x To Signed	Hardware Multiply	35	40	4.0 μs	16.0 μs	40 μs	

### TABLE 9-1: PERFORMANCE COMPARISON FOR VARIOUS MULTIPLY OPERATIONS





Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	66
LATC	LATC Output Latch Register								66
TRISC	PORTC Data Direction Register								66

### TABLE 11-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
PORTE	RE7	RE6	RE5	RE4	RE3	RE2	RE1	RE0	66
LATE	LATE Output Latch Register								66
TRISE	PORTE Data Direction Register								66

TABLE 11-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORT
--

### 16.0 CAPTURE/COMPARE/PWM (CCP) MODULES

PIC18F6310/6410/8310/8410 devices have three CCP (Capture/Compare/PWM) modules, labelled CCP1, CCP2 and CCP3. All modules implement standard Capture, Compare and Pulse-Width Modulation (PWM) modes.

Each CCP module contains a 16-bit register which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register. For the sake of clarity, all CCP module operation in the following sections is described with respect to CCP2, but are equally applicable to CCP1 and CCP3.

### REGISTER 16-1: CCPxCON: CCP1/CCP2/CCP3 CONTROL REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_		DCxB1	DCxB0	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6	Unimplemented: Read as '0'					
bit 5-4	DCxB<1:0>: PWM Duty Cycle bit 1 and bit 0 for CCP Module x					
	Capture mode:					
	Unused.					
	Compare mode:					
	Unused.					
	PWM mode:					
	These bits are the two Least Significant bits (bit 1 and bit 0) of the 10-bit PWM Duty Cycle register. The eight Most Significant bits (DCx<9:2>) of the PWM Duty Cycle are found in CCPRxL.					
bit 3-0	CCPxM<3:0>: CCP Module x Mode Select bits					
	0000 = Capture/Compare/PWM disabled (resets CCPx module)					
	0001 = Reserved					
	0010 = Compare mode, toggle output on match (CCPxIF bit is set)					
	0011 = Reserved					
	0100 = Capture mode, every falling edge					
	0101 = Capture mode, every rising edge					
	0110 = Capture mode, every 4th rising edge					
	0111 = Capture mode, every toth fising edge					
	(CCPxIE bit is set)					
	1001 = Compare mode: initialize CCPx pin high: on compare match, force CCPx pin low					
	(CCPxIF bit is set)					
	1010 = Compare mode: generate software interrupt on compare match (CCPxIF bit is set,					
	CCPx pin reflects I/O state)					
	1011 = Compare mode: trigger special event, reset timer, start A/D conversion on $(12)$					
	CCPx match (CCPxIF bit is set)					
	11xx = PWW mode					
Note 1:	The Special Event Trigger on CCP1 will reset the timer but not start an A/D conversion on a CCP1 match.					

2: For CCP3, the Special Event Trigger is not available. This mode functions the same as Compare Generate Interrupt mode (CCP3M<3:0> = 1010).

### 16.2.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit, CCP2IE (PIE2<1>), clear to avoid false interrupts and should clear the flag bit, CCP2IF, following any such change in operating mode.

### 16.2.4 CCP PRESCALER

There are four prescaler settings in Capture mode; they are specified as part of the operating mode selected by the mode select bits (CCP2M<3:0>). Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore, the first capture may be from a non-zero prescaler. Example 16-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

#### EXAMPLE 16-1: CHANGING BETWEEN CAPTURE PRESCALERS

CLRF	CCP2CON	;	Turn CCP module off
MOVLW	NEW_CAPT_PS	;	Load WREG with the
		;	new prescaler mode
		;	value and CCP ON
MOVWF	CCP2CON	;	Load CCP2CON with
		;	this value

### 16.3 Compare Mode

In Compare mode, the 16-bit CCPR2 register value is constantly compared against either the TMR1 or TMR3 register pair value. When a match occurs, the CCP2 pin can be:

- driven high
- driven low
- toggled (high-to-low or low-to-high)
- remain unchanged (that is, reflects the state of the I/O latch)

The action on the pin is based on the value of the mode select bits (CCP2M<3:0>). At the same time, the interrupt flag bit, CCP2IF, is set.

### 16.3.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the appropriate TRIS bit.

Note:	Clearing the CCPxCON register will force
	the RC1 or RE7 compare output latch
	(depending on device configuration) to the
	default low level. This is not the PORTC or
	PORTE I/O data latch.

### 16.3.2 TIMER1/TIMER3 MODE SELECTION

Timer1 and/or Timer3 must be running in Timer mode, or Synchronized Counter mode, if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

### 16.3.3 SOFTWARE INTERRUPT MODE

When the Generate Software Interrupt mode is chosen (CCP2M<3:0> = 1010), the CCP2 pin is not affected. Only a CCP interrupt is generated if enabled and the CCP2IE bit is set.

### 16.3.4 SPECIAL EVENT TRIGGERS

CCP1 and CCP2 are both equipped with a Special Event Trigger. This is an internal hardware signal, generated in Compare mode, to trigger actions by other modules. The Special Event Trigger is enabled by selecting the Compare Special Event Trigger mode (CCP2M<3:0> = 1011).

For either CCP module, the Special Event Trigger resets the Timer register pair for whichever timer resource is currently assigned as the module's time base. This allows the CCPRx registers to serve as a programmable period register for either timer.

The Special Event Trigger for CCP2 can also start an A/D conversion. In order to do this, the A/D Converter must already be enabled.

Note:	The Special Event Trigger of CCP1 only							
	resets Timer1/Timer3 and cannot start an							
	A/D conversion even when the A/D							
	Converter is enabled.							

CCP3 is not equipped with a Special Event Trigger. Selecting the Compare Special Event Trigger mode for this device (CCP3M<3:0> = 1011) is functionally the same as selecting the Generate Software Interrupt mode (CCP3M<3:0> = 1010).

















### TABLE 25-1: OPCODE FIELD DESCRIPTIONS

Field	Description					
a	RAM access bit					
	a = 0: RAM location in Access RAM (BSR register is ignored)					
	a = 1: RAM bank is specified by BSR register					
	Bit address within an 8-bit file register (0 to 7).					
BSR	Bank Select Register. Used to select the current RAM bank.					
C, DC, Z, OV, N						
a	d = $0^{\circ}$ store result in WREG					
	d = 1: store result in file register f.					
dest	Destination: either the WREG register or the specified register file location.					
f	8-bit register file address (00h to FFh), or 2-bit FSR designator (0h to 3h).					
fs	12-bit register file address (000h to FFFh). This is the source address.					
fd	12-bit register file address (000h to FFFh). This is the destination address.					
GIE	Global interrupt enable bit.					
k	Literal field, constant data or label (may be either an 8-bit, 12-bit or a 20-bit value).					
label	Label name.					
mm	The mode of the TBLPTR register for the table read and table write instructions.					
	Only used with table read and table write instructions:					
*	No change to register (such as TBLPTR with table reads and writes).					
*+	Post-Increment register (such as TBLPTR with table reads and writes).					
*_	Post-Decrement register (such as TBLPTR with table reads and writes).					
+*	Pre-Increment register (such as TBLPTR with table reads and writes).					
n	The relative address (2's complement number) for relative branch instructions, or the direct address for					
	cali/branch and return instructions.					
PC	Program Counter.					
PCL	Program Counter Lick Byte.					
	Program Counter High Byte.					
DCLATH	Program Counter Linner Byte Latch					
	Power-Down hit					
PRODH	Product of Multiply high byte					
PRODI	Product of Multiply low byte					
s	East Call/Return mode select bit					
~	s = 0: do not update into/from shadow registers					
	s = 1: certain registers loaded into/from shadow registers (Fast mode)					
TBLPTR	21-bit Table Pointer (points to a program memory location).					
TABLAT	8-bit Table Latch.					
TO	Time-out bit.					
TOS	Top-of-Stack.					
u	Unused or Unchanged.					
WDT	Watchdog Timer.					
WREG	Working register (accumulator).					
x	Don't care ('0' or '1'). The assembler will generate code with $x = 0$ . It is the recommended form of use for					
	Z bit offect value for indirect addressing of register files (course)					
Z <sub>S</sub>	7-bit offset value for indirect addressing of register files (destination)					
2d	Ontional argument					
[text]	Indicates an indexed address					
(text)	The contents of text					
[expr] <n></n>	Specifies bit n of the register indicated by the pointer expr					
→	Assigned to.					
< >	Register bit field.					
e	In the set of.					
italics	User-defined term (font is Courier New).					

BRA	4	Uncondit	Unconditional Branch				
Synt	ax:	BRA n	BRA n				
Oper	rands:	-1024 ≤ n ≤	1023		Operands:		
Ope	ration:	(PC) + 2 + 2	$2n \rightarrow PC$				
Statu	is Affected:	None			Onenetier		
Enco	oding:	1101	0nnn nnr	nn nnnn	Operation:		
Desc	cription:	Add the 2's the PC. Sin incremente instruction, PC + 2 + 2r two-cycle ir	LLLLLLStatus /Add the 2's complement number '2n' to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is a two-cycle instruction.Encodir Descrip				
Word	ds:	1					
Cycl	es:	2					
QC	ycle Activity:						
	Q1	Q2	Q3	Q4			
Decode		Read literal 'n'	Process Data	Write to PC	Words: Cycles:		
	No operation	No operation	No operation	No operation	Q Cycle A		
<u>Exar</u>	<u>nple:</u>	HERE	BRA Jump		De		
	PC PC After Instruction PC	etion = ad on = ad	dress (HERE)	)	<u>Example:</u> Befor I After		

BSF	Bit Set f						
Syntax:	Syntax: BSF f, b {,a}						
Operands:	$0 \le f \le 255$ $0 \le b \le 7$ $a \in [0,1]$	$0 \le f \le 255$ $0 \le b \le 7$ $a \in [0,1]$					
Operation:	$1 \rightarrow f < b >$						
Status Affected:	None						
Encoding:	1000	bbba ff:	ff ffff				
Description:	Bit 'b' in reg If 'a' is '0', t If 'a' is '1', t GPR bank. If 'a' is '0' a set is enabl in Indexed mode when Section 25	Bit 'b' in register 'f' is set. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See Section 25.2.3 for details					
Words:	1	1					
Cycles:	1	1					
Q Cycle Activity:							
Q1	Q2	Q3	Q4				
Decode	Process Data	Write register 'f'					
Example:	BSF F	LAG_REG, 7	, 1				
Before Instruction FLAG_REG = 0Ah After Instruction FLAG_REG = 8Ah							

NEG	NEGF Negate f						
Synta	ax:	NEGF f{	NEGF f {,a}				
Oper	ands:	0 ≤ f ≤ 255 a ∈ [0,1]					
Oper	ation:	$(\overline{f}) + 1 \rightarrow f$	$(\overline{f}) + 1 \rightarrow f$				
Statu	s Affected:	N, OV, C, D	C, Z				
Enco	ding:	0110	110a	ffff	ffff		
Desc	ription:	Location 'f' complemen data memo lf 'a' is '0', tt If 'a' is '0', tt GPR bank. If 'a' is '0' a set is enabl in Indexed I mode when Section 25	Location 'f' is negated using two's complement. The result is placed in the data memory location 'f'. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See Section 25.2.3 for details.				
Word	ls:	1	1				
Cycle	es:	1					
QC	ycle Activity:						
	Q1	Q2	Q	3	Q4		
Decode Read Process Write register 'f' Data register 'f							
Example: NEGF REG, 1 Before Instruction							

NOF	NOP No Operation						
Synta	ax:	NOP					
Oper	ands:	None					
Oper	ation:	No operati	on				
Statu	s Affected:	None					
Encoding:		0000	0000	000	0	0000	
		1111	XXXX	xxxx		xxxx	
Desc	ription:	No operati	No operation.				
Word	ls:	1	1				
Cycle	es:	1					
Q Cycle Activity:							
	Q1	Q2 Q3				Q4	
	Decode	No No No			No		
		operation	operation operation operation			peration	

#### Example:

None.

 REG
 =
 0011
 1010
 [3Ah]

 After Instruction
 REG
 =
 1100
 0110
 [C6h]

## 26.0 DEVELOPMENT SUPPORT

The PIC<sup>®</sup> microcontrollers and dsPIC<sup>®</sup> digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
- MPLAB<sup>®</sup> IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM<sup>™</sup> Assembler
  - MPLINK<sup>™</sup> Object Linker/ MPLIB<sup>™</sup> Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- · Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit<sup>™</sup> 3 Debug Express
- Device Programmers
  - PICkit<sup>™</sup> 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

### 26.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows<sup>®</sup> operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- · A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- · High-level source code debugging
- · Mouse over variable inspection
- Drag and drop variables from source to watch windows
- · Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- · Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

### 27.2 DC Characteristics: Power-Down and Supply Current PIC18F6310/6410/8310/8410 (Industrial, Extended) PIC18LF6310/6410/8310/8410 (Industrial) (Continued)

PIC18LF6310/6410/8310/8410 (Industrial)		Standard Operating Conditions (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial							
PIC18F6310/6410/8310/8410 (Industrial, Extended)		$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Device	Тур	Max	Units	Conditions				
	Module Differential Currents	ule Differential Currents (ΔΙωστ, ΔΙΒΟR, ΔΙLVD, ΔΙΟSCΒ, ΔΙΑΟ)							
D022	Watchdog Timer	1.7	4.0	μA	-40°C				
(∆IWDT)		2.1	4.0	μA	+25°C	VDD = 2.0V			
		2.6	5.0	μA	+85°C				
		2.2	6.0	μA	-40°C				
		2.4	6.0	μΑ	+25°C	VDD = 3.0V			
		2.8	7.0	μΑ	+85°C				
		2.9	10.0	μA	-40°C				
		3.1	10.0	μA	+25°C				
		3.3	13.0	μA	+85°C	VDD - 5.0V			
		20	190	μA	+125°C				
D022A	Brown-out Reset <sup>(4)</sup>	17	50.0	μΑ	-40°C to +85°C	VDD = 3.0V			
$(\Delta   BOR)$		47	60.0	μA	-40°C to +85°C				
		90	200	μA	-40°C to +125°C	VDD = 5.0V			
D022B	High/Low-Voltage Detect (4)	14	38.0	μΑ	-40°C to +85°C	VDD = 2.0V			
(∆ILVD)		18	40.0	μA	-40°C to +85°C	VDD = 3.0V			
		21	45.0	μA	-40°C to +85°C				
		90	2000	μA	-40°C to +125°C	VDD - 5.0V			
D025	Timer1 Oscillator	1.0	3.5	μA	-40°C		32 kHz on Timer1 <sup>(4)</sup>		
(∆IOSCB)		1.1	3.5	μA	+25°C	VDD = 2.0V			
		1.1	4.5	μA	+70°C				
		1.2	4.5	μA	-40°C		32 kHz on Timer1 <sup>(4)</sup>		
		1.3	4.5	μA	+25°C	VDD = 3.0V			
		1.2	5.5	μA	+70°C				
		1.8	6.0	μA	-40°C				
		1.9	6.0	μA	+25°C	VDD = 5.0V	32 kHz on Timer1 <sup>(4)</sup>		
		1.9	7.0	μA	+85°C				
D026	A/D Converter	1.0	3.0	μA	—	VDD = 2.0V			
(∆IAD)		1.0	4.0	μA	—	VDD = 3.0V VDD = 5.0V	A/D on, not converting,		
		1.0	8.0	μA	—		$1.6~\mu s \leq T \text{AD} \leq 6.4~\mu s$		
		15	60	μA	+125°C				

**Legend:** Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or Vss, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins are tri-stated, pulled to VDD or VSS; MCLR = VDD; WDT is enabled/disabled as specified.

**3:** When operation below -10°C is expected, use the T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.